

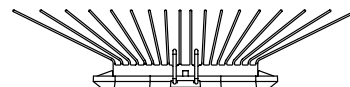


Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-51190K-C2-R0

Features & Benefits

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- » Comes preassembled with high performance, phase changing, thermal interface material
- » Designed for low profile components from 1.5 to 2.99mm



**Image above is for illustration purposes only.*

Thermal Performance

AIR VELOCITY

FT/MIN

M/S

200

1.0

300

1.5

400

2.0

500

2.5

600

3.0

700

3.5

800

4.0

THERMAL RESISTANCE

°C/W (UNDUCTED FLOW)

°C/W (DUCTED FLOW)

10.1

7.9

8.3

7.2

6.4

5.9

5.5

5.1

Product Details

DIMENSION A

DIMENSION B

DIMENSION C

DIMENSION D

INTERFACE MATERIAL

FINISH

19 mm

19 mm

14.5 mm

34.8 mm

SAINT-GOBAIN C1100F

BLACK- ANODIZED

NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) ATS-51190K-C1-R0 is a substitute item available utilizing an equivalent phase change material (Chomerics T766).
- 3) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 4) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT190
- 6) Contact ATS to learn about custom options available.



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SOLUTIONS, INC.
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For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).